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Page(s): 176 -178

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Page(s): 525 -532

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Integrated Reliability Workshop Final Report, 1997 IEEE International , 1997

Page(s): 142 -143

[\[Abstract\]](#) [\[PDF Full-Text \(192 KB\)\]](#) **CNF****4 Effects of water vap r anneal on MIS devices made of nitrided gate dielectrics***Xiewen Wang; Khare, M.; Ma, T.P.*

VLSI Technology, 1996. Digest of Technical Papers. 1996 Symposium on , 1996

Page(s): 226 -227

[\[Abstract\]](#) [\[PDF Full-Text \(152 KB\)\]](#) **CNF**

5 Water-related degradation of contacts in the multilevel MOS IC with spin-o glasses as interlevel dielectrics

Lifshitz, N.; Lai, W.Y.C.; Smolinsky, G.

IEEE Electron Device Letters , Volume: 10 Issue: 12 , Dec. 1989

Page(s): 562 -564

[\[Abstract\]](#) [\[PDF Full-Text \(224 KB\)\]](#) **JNL**

6 Advances in processing techniques for silicon micromechanical devices wit smooth surfaces

Guckel, H.; Sniegowski, J.J.; Christenson, T.R.

Micro Electro Mechanical Systems, 1989, Proceedings, An Investigation of Micro Structures, Sensors, Actuators, Machines and Robots. IEEE , 1989

Page(s): 71 -75

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IEEE Electron Device Letters, Volume: 22 Issue: 4, April 2001

Page(s): 176 -178

[\[Abstract\]](#) [\[PDF Full-Text \(56 KB\)\]](#) **JNL****2 Fluorine ion implantation into silicon dioxide to form stable low-k internet dielectric films***Essaian, S.; Rosenblatt, D.H.*

Ion Implantation Technology, 2000. Conference on, 2000

Page(s): 330 -333

[\[Abstract\]](#) [\[PDF Full-Text \(256 KB\)\]](#) **CNF****3 Micromachined ultrasonic transducers using silicon nitride membrane fabricated in PECVD technology***Caliano, G.; Galanella, F.; Caronti, A.; Carotenuto, R.; Pappalardo, M.; Foglietti, V.; Lamberti, N.*

Ultrasonics Symposium, 2000 IEEE, Volume: 1, 2000

Page(s): 963 -968 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(604 KB\)\]](#) **CNF****4 Comparison between HDP CVD and PECVD silicon nitride for advanced interconnect applications***Yota, J.; Janani, M.; Camilletti, L.E.; Kar-Roy, A.; Liu, Q.Z.; Nguyen, C.; Woo, M.D.; Hander, J.; van Cleemput, P.; Chang, W.; Chiou, W.C.; Li, L.J.; Chao, L.C.; Jang, S.M. Yu, C.H.; Liang, M.S.*

Interconnect Technology Conference, 2000. Proceedings of the IEEE 2000 International
, 2000
Page(s): 76 -78

[\[Abstract\]](#) [\[PDF Full-Text \(260 KB\)\]](#) [CNF](#)

5 Electrical and reliability characteristics of an ultrathin TaO/_xN/_y gate dielectric prepared by ND/₃/ annealing of Ta/₂O/₅
Hyungsuk Jung; Kiju Im; Dooyoung Yang; Hyunsang Hwang
IEEE Electron Device Letters , Volume: 21 Issue: 12 , Dec. 2000
Page(s): 563 -565

[\[Abstract\]](#) [\[PDF Full-Text \(64 KB\)\]](#) [JNL](#)

6 Insulator investigation on SiC for improved reliability
Lipkin, L.A.; Palmour, J.W.
Electron Devices, IEEE Transactions on , Volume: 46 Issue: 3 , March 1999
Page(s): 525 -532

[\[Abstract\]](#) [\[PDF Full-Text \(176 KB\)\]](#) [JNL](#)

7 Effects of N distribution on charge trapping and TDDB characteristics of N/₂O annealed wet oxide
Mazumder, M.K.; Teramoto, A.; Komori, J.; Sekine, M.; Kawazu, S.; Mashiko, Y.
Electron Devices, IEEE Transactions on , Volume: 46 Issue: 6 , June 1999
Page(s): 1121 -1126

[\[Abstract\]](#) [\[PDF Full-Text \(180 KB\)\]](#) [JNL](#)

8 Anodization for forming thin film embedded capacitors in MCM-D and MCM substrates
Nelms, D.; Ulrich, R.; Schaper, L.; Reeder, S.
Electronic Components & Technology Conference, 1998. 48th IEEE , 1998
Page(s): 247 -251

[\[Abstract\]](#) [\[PDF Full-Text \(476 KB\)\]](#) [CNF](#)

9 Degradation of the characteristics of p/₊ poly MOS capacitors with N nitrided gate oxide due to post nitrogen annealing
Mazumder, M.K.; Teramoto, A.; Kobayashi, K.; Sekine, M.; Kawazu, S.; Koyama, H.
Integrated Reliability Workshop Final Report, 1997 IEEE International , 1997
Page(s): 142 -143

[\[Abstract\]](#) [\[PDF Full-Text \(192 KB\)\]](#) [CNF](#)

10 Effect of N/sub 2/O r NO annealing of v oxide at different times on TDDDB characteristics

Mazumder, M.K.; Teramoto, A.; Kobayashi, K.; Katsumata, M.; Mashiko, Y.; Sekine, Koyama, H.; Yasuoka, A.

Integrated Reliability Workshop, 1996., IEEE International

Page(s): 125 -133

[\[Abstract\]](#) [\[PDF Full-Text \(780 KB\)\]](#) [CNF](#)

11 Effects of water vapor anneal on MIS devices made of nitrided gate dielectrics

Xiewen Wang; Khare, M.; Ma, T.P.

VLSI Technology, 1996. Digest of Technical Papers. 1996 Symposium on , 1996

Page(s): 226 -227

[\[Abstract\]](#) [\[PDF Full-Text \(152 KB\)\]](#) [CNF](#)

12 The electrical breakdown properties of low density polyethylene film due morphological change

Nung-Pyo Hong; Pil-Gyu Im; Deok-Jung Kim; Kyung-Soon Cho; Don-Chan Cho; Yong-Woo Lee; Jin-Woong Hong

Electrical Insulation and Dielectric Phenomena, 1996., IEEE 1996 Annual Report of th Conference on , Volume: 2 , 1996

Page(s): 692 -696 vol.2

[\[Abstract\]](#) [\[PDF Full-Text \(388 KB\)\]](#) [CNF](#)

13 Novel oxynitridation technology for highly reliable thin dielectrics

Moon-Sig Joo; Seok-Hee Lee; Seok-Kiu Lee; Byung-Jin Cho; Jong-Choul Kim; Soo-Ha Choi

VLSI Technology, 1995. Digest of Technical Papers. 1995 Symposium on , 1995

Page(s): 107 -108

[\[Abstract\]](#) [\[PDF Full-Text \(124 KB\)\]](#) [CNF](#)

14 Development of polyethylene insulation diagnosis of high voltage cables i France

Clavreul, R.; Duchateau, F.

Electrical Insulating Materials, 1995. International Symposium on , 1995

Page(s): 27 -30

[\[Abstract\]](#) [\[PDF Full-Text \(224 KB\)\]](#) [CNF](#)

15 Water diffusion model for the enhancement of hot-carrier-induced degradation due t silicon nitride passivation in submicron MOSFET's

Shimaya, M.

Reliability Physics Symposium, 1995. 33rd Annual Proceedings., IEEE International ,

1995

Page(s): 292 -296

[\[Abstract\]](#) [\[PDF Full-Text \(360 KB\)\]](#) [CNF](#)

16 Unified model for boron diffusion in thin gate oxides: effects of F , H /sub 2 N , oxide thickness and injected Si interstitials*Fair, R.B.*

Electron Devices Meeting, 1995., International , 1995

Page(s): 85 -88

[\[Abstract\]](#) [\[PDF Full-Text \(300 KB\)\]](#) [CNF](#)

17 The formation of a fine-patterned ferroelectric thin film from a sol-gel solution containing a photo-sensitive water-generator*Soyama, N.; Sasaki, G.; Atsuki, T.; Yonezawa, T.; Ogi, K.*

Applications of Ferroelectrics, 1994.ISAF '94., Proceedings of the Ninth IEEE International Symposium on , 1994

Page(s): 408 -411

[\[Abstract\]](#) [\[PDF Full-Text \(284 KB\)\]](#) [CNF](#)

18 Electrical properties of PZT thin films derived from sol-gel solution containing photo-sensitive water-generator*Nakao, Y.; Nakamura, T.; Kamisawa, A.; Takasu, H.; Soyama, N.; Sasaki, G.; Atsuki, T.; Yonezawa, T.; Ogi, K.*

Applications of Ferroelectrics, 1994.ISAF '94., Proceedings of the Ninth IEEE International Symposium on , 1994

Page(s): 450 -453

[\[Abstract\]](#) [\[PDF Full-Text \(504 KB\)\]](#) [CNF](#)

19 Water induced TSDC in hemoglobin and myoglobin*Bridelli, M.G.; Capelletti, R.; Losi, S.; Mozzarelli, A.; Vecchi, A.*

Electrets, 1994. (ISE 8), 8th International Symposium on , 1994

Page(s): 869 -874

[\[Abstract\]](#) [\[PDF Full-Text \(252 KB\)\]](#) [CNF](#)

20 Studies on the high temperature superconductor (HTS)/metal/polymer dielectric interconnect structure for packaging applications*Paik, K.W.; Mogro-Campero, A.*

Electronic Components and Technology Conference, 1994. Proceedings., 44th , 1994

Page(s): 362 -366

[\[Abstract\]](#) [\[PDF Full-Text \(488 KB\)\]](#) [CNF](#)

21 Studies on the high-temperature superconductor (HTS)/metal/polymer dielectric interconnect structure for packaging applications

Paik, K.W.; Mogro-Campero, A.

Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology IEEE Transactions on] , Volume: 17 Issue: 3 , Aug. 1994

Page(s): 435 -441

[\[Abstract\]](#) [\[PDF Full-Text \(732 KB\)\]](#) [JNL](#)

22 Suppression of the MOS transistor hot carrier degradation caused by water desorbed from intermetal dielectric

Shimokawa, K.; Usami, T.; Tokitou, S.; Hirashita, N.; Yoshimaru, M.; Ino, M.

VLSI Technology, 1992. Digest of Technical Papers. 1992 Symposium on , 1992

Page(s): 96 -97

[\[Abstract\]](#) [\[PDF Full-Text \(160 KB\)\]](#) [CNF](#)

23 A study of oxidation in water trees using IR-microspectroscopy in polyethylene laboratory models

Koo, J.Y.; Bouzerara, R.; Kim, J.T.; Filippini, J.C.

Electrical Insulation and Dielectric Phenomena, 1990. Annual Report., Conference on 1990

Page(s): 494 -501

[\[Abstract\]](#) [\[PDF Full-Text \(272 KB\)\]](#) [CNF](#)

24 Advances in processing techniques for silicon micromechanical devices with smooth surfaces

Guckel, H.; Sniegowski, J.J.; Christenson, T.R.

Micro Electro Mechanical Systems, 1989, Proceedings, An Investigation of Micro Structures, Sensors, Actuators, Machines and Robots. IEEE , 1989

Page(s): 71 -75

[\[Abstract\]](#) [\[PDF Full-Text \(604 KB\)\]](#) [CNF](#)

25 The influence of structure on water treeing in crosslinked polyethylene: crystallization and annealing effects in bow-tie tree growth

Phillips, P.J.; Karakelle, M.

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation IEEE Transactions on] , Volume: 24 Issue: 6 , Dec. 1989

Page(s): 1093 -1100

[\[Abstract\]](#) [\[PDF Full-Text \(504 KB\)\]](#) [JNL](#)
